

## Applications

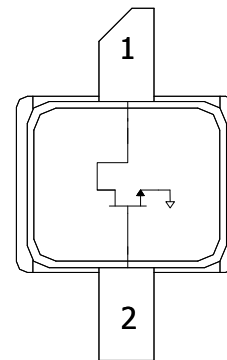
- Military radar
- Civilian radar
- Professional and military radio communications
- Test instrumentation
- Wideband or narrowband amplifiers
- Jammers



## Product Features

- Frequency: DC to 6 GHz
- Output Power ( $P_{3dB}$ ): 42.7 W at 3 GHz
- Linear Gain: >14 dB at 3 GHz
- Operating Voltage: 28 V
- Low thermal resistance package

## Functional Block Diagram



## General Description

The Qorvo T2G6003028-FS is a 30W ( $P_{3dB}$ ) discrete GaN on SiC HEMT which operates from DC to 6 GHz. The device is constructed with Qorvo's proven QGaN25 process, which features advanced field plate techniques to optimize power and efficiency at high drain bias operating conditions. This optimization can potentially lower system costs in terms of fewer amplifier line-ups and lower thermal management costs.

Lead-free and ROHS compliant

Evaluation boards are available upon request.

## Pin Configuration

Pin No.	Label
1	$V_D$ / RF OUT
2	$V_G$ / RF IN
Flange	Source

## Ordering Information

Part	ECCN	Description
T2G6003028-FS	EAR99	Packaged part Flangeless
T2G6003028-FS-EVB1	EAR99	5.4 – 5.9 GHz Evaluation Board
T2G6003028-FS-EVB2	EAR99	1.3 – 1.9 GHz Evaluation Board

### Absolute Maximum Ratings

Parameter	Value
Breakdown Voltage ( $V_{D0}$ )	100 V
Gate Voltage Range ( $V_G$ )	-7 to 0 V
Drain Current ( $I_D$ )	5.5 A
Gate Current ( $I_G$ )	-10 to 28 mA
Power Dissipation ( $P_D$ )	47.5 W
RF Input Power, CW, $T = 25^\circ\text{C}$ ( $P_{IN}$ )	40 dBm
Channel Temperature ( $T_{CH}$ )	275 $^\circ\text{C}$
Mounting Temperature (30 Seconds)	320 $^\circ\text{C}$
Storage Temperature	-40 to 150 $^\circ\text{C}$

Operation of this device outside the parameter ranges given above may cause permanent damage. These are stress ratings only, and functional operation of the device at these conditions is not implied.

### Recommended Operating Conditions<sup>(1)</sup>

Parameter	Value
Drain Voltage Range ( $V_D$ )	12 - 40 V
Drain Quiescent Current ( $I_{DQ}$ )	200 mA (Typ.)
Peak Drain Current ( $I_D$ )	1.7 A (Typ.)
Gate Voltage ( $V_G$ )	-3.3 V (Typ.)
Channel Temperature ( $T_{CH}$ )	225 $^\circ\text{C}$ (Max)
Power Dissipation, CW ( $P_D$ )	35 W (Max)
Power Dissipation, Pulse ( $P_D$ ) <sup>(2)</sup>	40 W (Max)

- Electrical specifications are measured at specified test conditions. Specifications are not guaranteed over all recommended operating conditions.
- Pulse Width = 380  $\mu\text{s}$ , Duty Cycle = 50%

### RF Characterization – Optimum Power Tuned Load Pull Performance

Test conditions unless otherwise noted:  $T = 25^\circ\text{C}$ .

Parameter	Typical Value						Units
	1	2	3	4	5	6	
Frequency (F)	1	2	3	4	5	6	GHz
Drain Voltage ( $V_D$ )	28	28	28	28	28	28	V
Bias Current ( $I_{DQ}$ )	200	200	200	200	200	200	mA
Output P3dB ( $P_{3dB}$ )	45.7	46	46.3	46.5	46.8	46.2	dBm
PAE @ P3dB ( $PAE_{3dB}$ )	64.9	64.2	68.1	54.6	55.9	54.7	%
Gain @ P3dB ( $G_{3dB}$ )	19.9	15.7	11.3	10.1	10.7	12.1	dB

Notes:

- $V_d = 28\text{ V}$ ,  $I_{dq} = 200\text{ mA}$ , Pulse Width = 100  $\mu\text{s}$ , Duty Cycle = 20%
- Characteristic Impedance ( $Z_0$ ) = 10  $\Omega$ . See pg. 18 for Load Pull Reference Planes.

### RF Characterization – Optimum Efficiency Tune Load Pull Performance

Test conditions unless otherwise noted:  $T = 25^\circ\text{C}$ .

Parameter	Typical Value						Units
	1	2	3	4	5	6	
Frequency (F)	1	2	3	4	5	6	GHz
Drain Voltage ( $V_D$ )	28	28	28	28	28	28	V
Bias Current ( $I_{DQ}$ )	200	200	200	200	200	200	mA
Output P3dB ( $P_{3dB}$ )	43.1	43.1	44.6	44.1	44.9	45.7	dBm
PAE @ P3dB ( $PAE_{3dB}$ )	73	76	46.1	65.1	69.5	60	%
Gain @ P3dB ( $G_{3dB}$ )	19.7	16.2	11.7	10.8	12.4	12.9	dB

Notes:

- $V_d = 28\text{ V}$ ,  $I_{dq} = 200\text{ mA}$ , Pulse Width = 100  $\mu\text{s}$ , Duty Cycle = 20%
- Characteristic Impedance ( $Z_0$ ) = 10  $\Omega$ . See pg. 18 for Load Pull Reference Planes.

## RF Characterization – Performance at 5.6 GHz <sup>(1, 2)</sup>

Symbol	Parameter	Min	Typical	Max	Units
G <sub>LIN</sub>	Linear Gain	12.0	14.0	17.0	dB
P <sub>3dB</sub>	Output Power at 3 dB Gain Compression	43.0	44.6	46.0	dBm
DE <sub>3dB</sub>	Drain Efficiency at 3 dB Gain Compression	45.0	54.0	70.0	%
G <sub>3dB</sub>	Gain at 3 dB Compression	9.0	11.0	14.0	dB

Notes:

1. Performance at 5.6 GHz in the 5.4 to 5.9 GHz Evaluation Board
2. V<sub>DS</sub> = 28 V, I<sub>DQ</sub> = 200 mA; Pulse: 100μs, 20%

## RF Characterization – Mismatch Ruggedness at 5.6 GHz <sup>(1)</sup>

Test conditions unless otherwise noted: T<sub>A</sub> = 25 °C, V<sub>D</sub> = 28 V, I<sub>DQ</sub> = 200 mA

Symbol	Parameter	Typical
VSWR	Impedance Mismatch Ruggedness	10:1

Notes:

1. P<sub>1dB</sub> CW Input Power under matched condition.

## Thermal and Reliability - CW <sup>(1)</sup>

Parameter	Test Conditions	Value	Units
Thermal Resistance, $\theta_{JC}$	$P_D = 30\text{ W}$ , $T_{base} = 85^\circ\text{C}$	3.82	$^\circ\text{C/W}$
Maximum Channel Temperature, $T_{CH}$		200	$^\circ\text{C}$
Median Lifetime, $T_M$		1.54E7	Hrs
Thermal Resistance, $\theta_{JC}$	$P_D = 35\text{ W}$ , $T_{base} = 85^\circ\text{C}$	4.01	$^\circ\text{C/W}$
Maximum Channel Temperature, $T_{CH}$		225	$^\circ\text{C}$
Median Lifetime, $T_M$		1.80E6	Hrs
Thermal Resistance, $\theta_{JC}$	$P_D = 40\text{ W}$ , $T_{base} = 85^\circ\text{C}$	4.22	$^\circ\text{C/W}$
Maximum Channel Temperature, $T_{CH}$		254	$^\circ\text{C}$
Median Lifetime, $T_M$		1.93E5	Hrs
Thermal Resistance, $\theta_{JC}$	$P_D = 45\text{ W}$ , $T_{base} = 85^\circ\text{C}$	4.43	$^\circ\text{C/W}$
Maximum Channel Temperature, $T_{CH}$		284	$^\circ\text{C}$
Median Lifetime, $T_M$		2.41E4	Hrs

Notes:

1. Thermal resistance calculated to bottom of package.

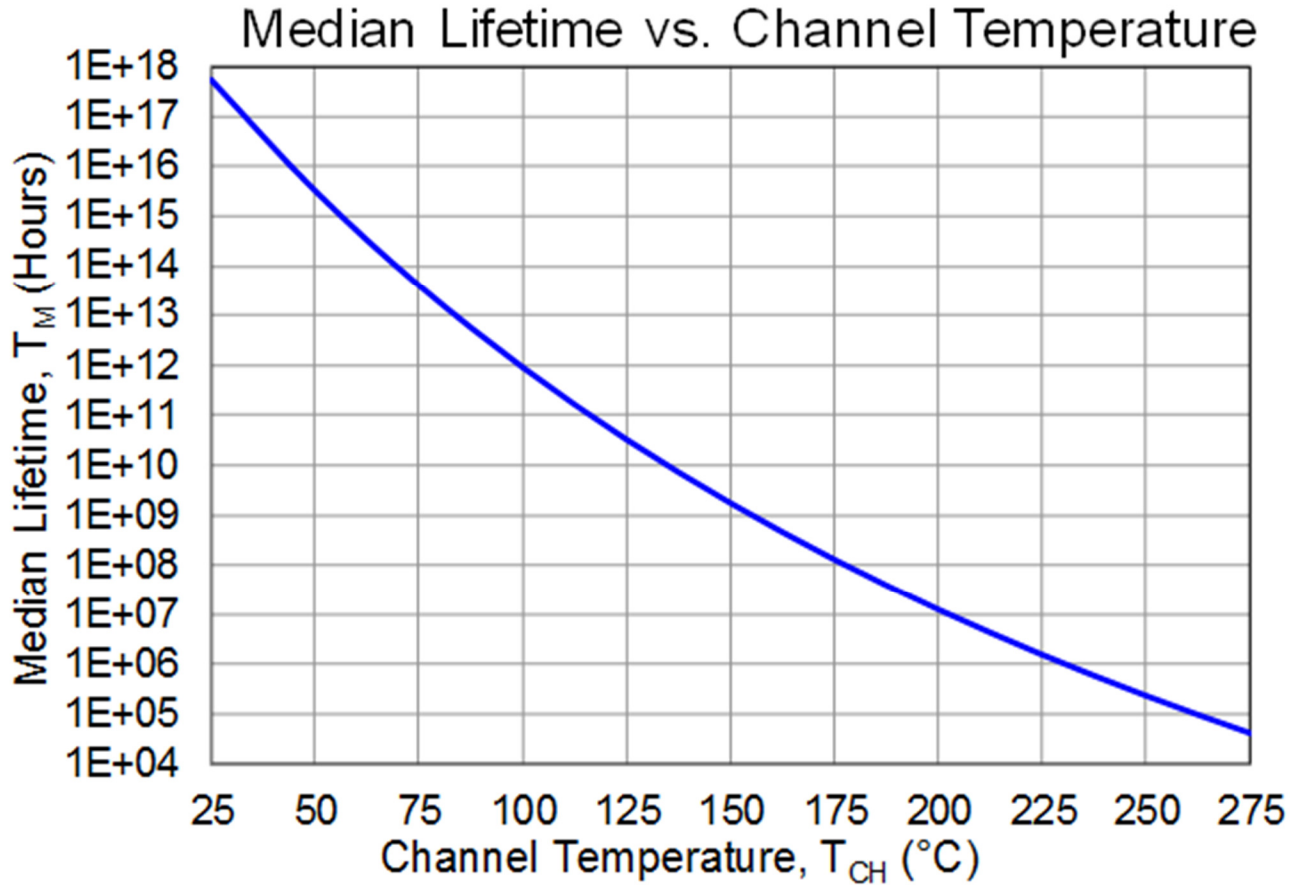
## Thermal and Reliability - Pulsed <sup>(1)</sup>

Parameter	Test Conditions	Value	Units
Thermal Resistance, $\theta_{JC}$	$P_D = 40\text{ W}$ , $T_{base} = 85^\circ\text{C}$ Pulse Width = 100 $\mu\text{s}$ Duty Cycle = 5%	2.33	$^\circ\text{C/W}$
Peak Channel Temperature, $T_{CH}$		178	$^\circ\text{C}$
Median Lifetime, $T_M$		2.52E9	Hrs
Thermal Resistance, $\theta_{JC}$	$P_D = 40\text{ W}$ , $T_{base} = 85^\circ\text{C}$ Pulse Width = 100 $\mu\text{s}$ Duty Cycle = 10%	2.43	$^\circ\text{C/W}$
Peak Channel Temperature, $T_{CH}$		182	$^\circ\text{C}$
Median Lifetime, $T_M$		8.60E8	Hrs
Thermal Resistance, $\theta_{JC}$	$P_D = 40\text{ W}$ , $T_{base} = 85^\circ\text{C}$ Pulse Width = 100 $\mu\text{s}$ Duty Cycle = 20%	2.68	$^\circ\text{C/W}$
Peak Channel Temperature, $T_{CH}$		192	$^\circ\text{C}$
Median Lifetime, $T_M$		1.65E8	Hrs
Thermal Resistance, $\theta_{JC}$	$P_D = 40\text{ W}$ , $T_{base} = 85^\circ\text{C}$ Pulse Width = 100 $\mu\text{s}$ Duty Cycle = 50%	3.18	$^\circ\text{C/W}$
Peak Channel Temperature, $T_{CH}$		212	$^\circ\text{C}$
Median Lifetime, $T_M$		1.10E7	Hrs

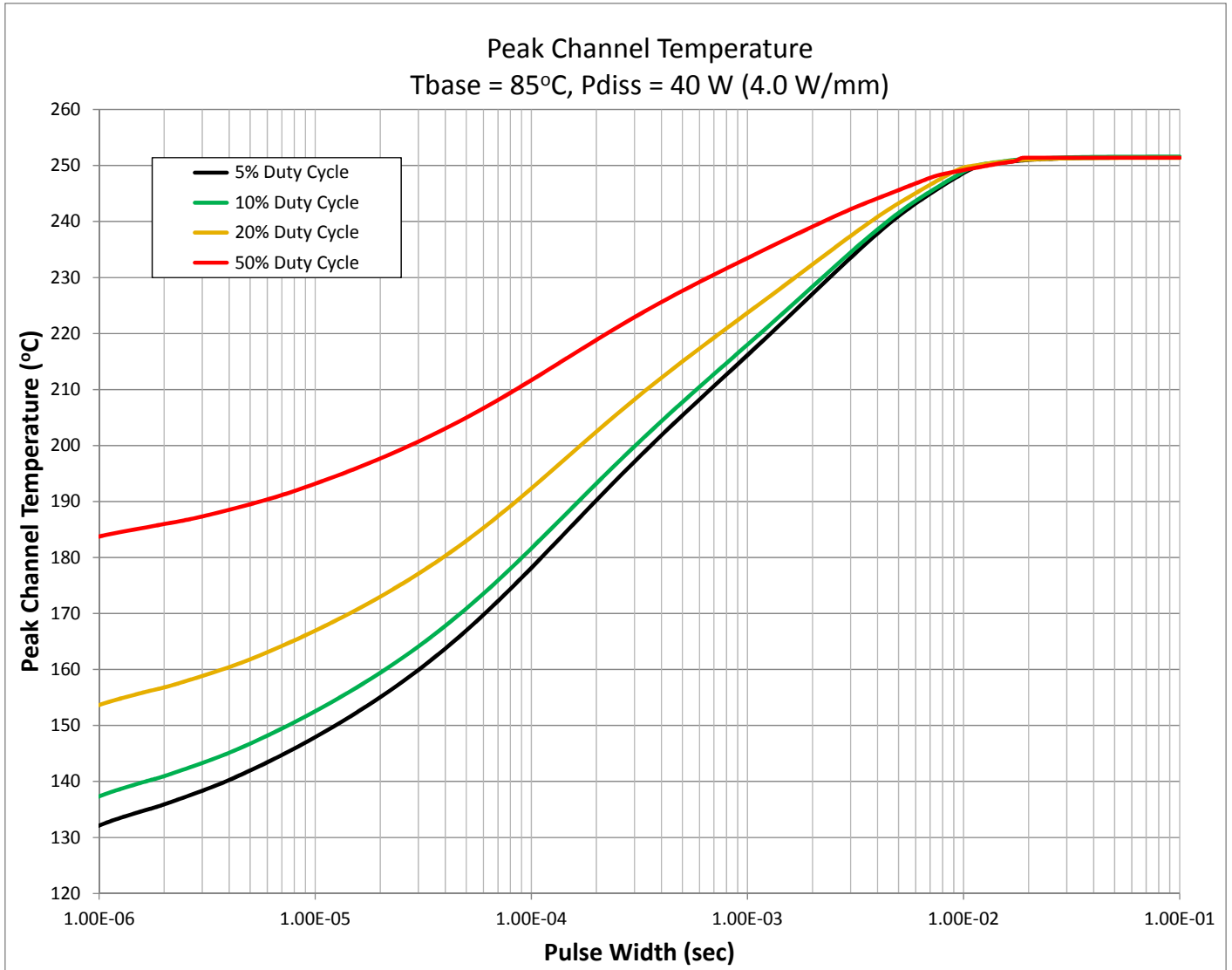
Notes:

2. Thermal resistance calculated to bottom of package.

**Median Lifetime**



## Maximum Channel Temperature

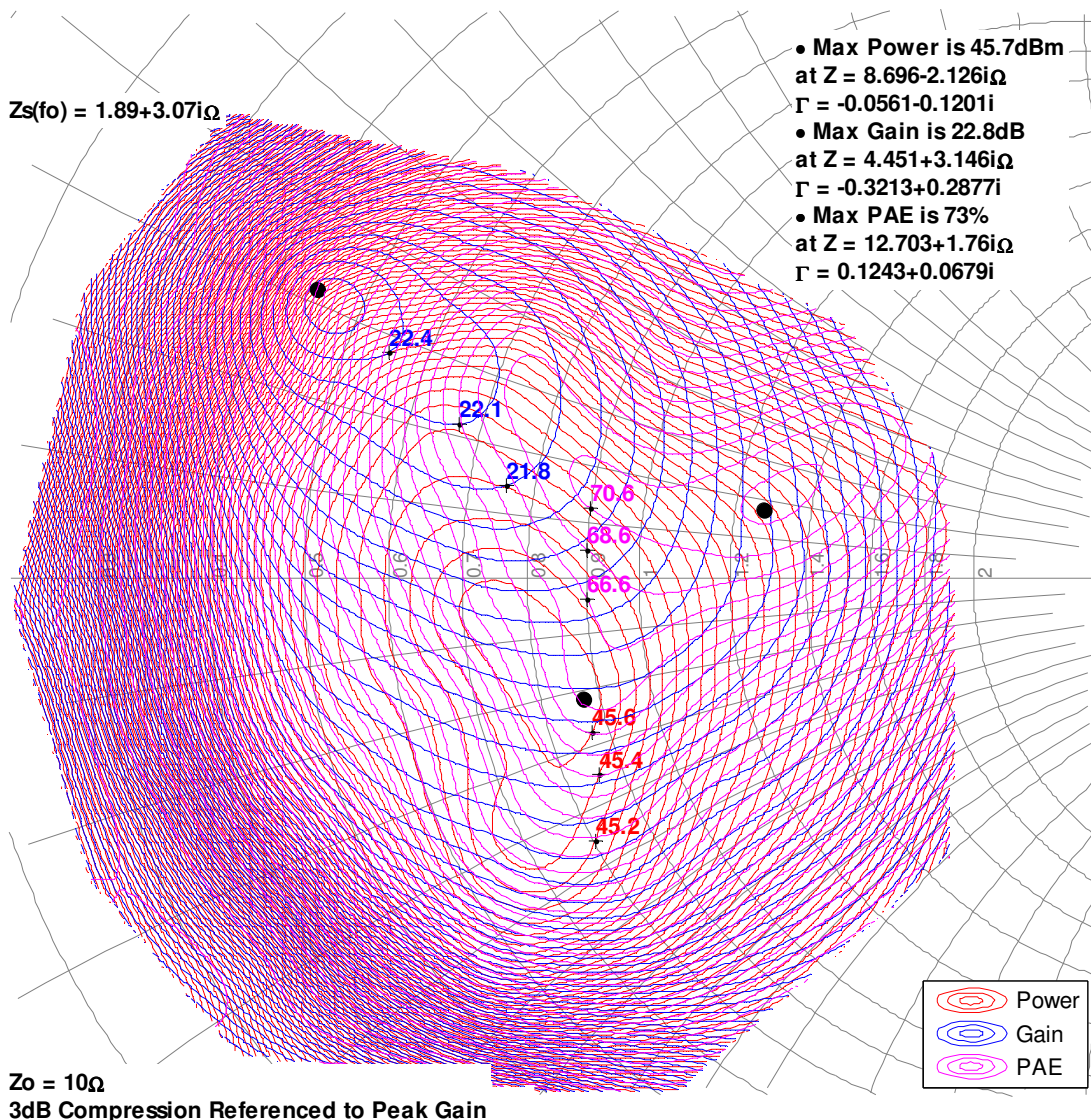


**Load Pull Smith Charts (1, 2, 3)**

Notes:

1. Test Conditions:  $V_{DS} = 28\text{ V}$ ,  $I_{DQ} = 200\text{ mA}$
2. Test Signal: Pulse Width = 100  $\mu\text{sec}$ , Duty Cycle = 20%
3. See pg. 18 for load pull reference planes.

**1GHz, Load-pull**



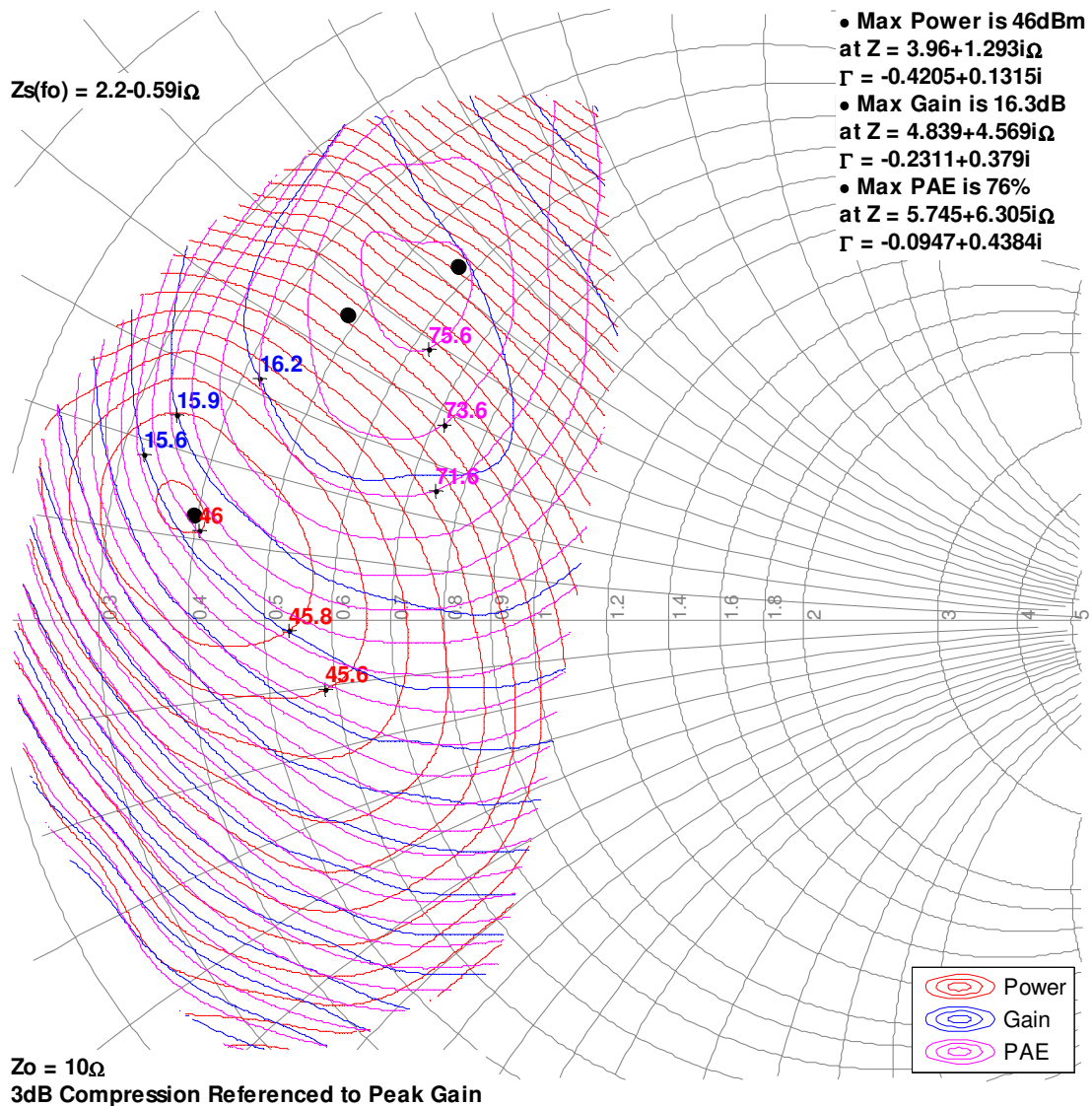


**Load Pull Smith Charts (1, 2, 3)**

Notes:

1. Test Conditions:  $V_{DS} = 28\text{ V}$ ,  $I_{DQ} = 200\text{ mA}$
2. Test Signal: Pulse Width = 100  $\mu\text{sec}$ , Duty Cycle = 20%
3. See pg. 18 for load pull reference planes.

**2GHz, Load-pull**



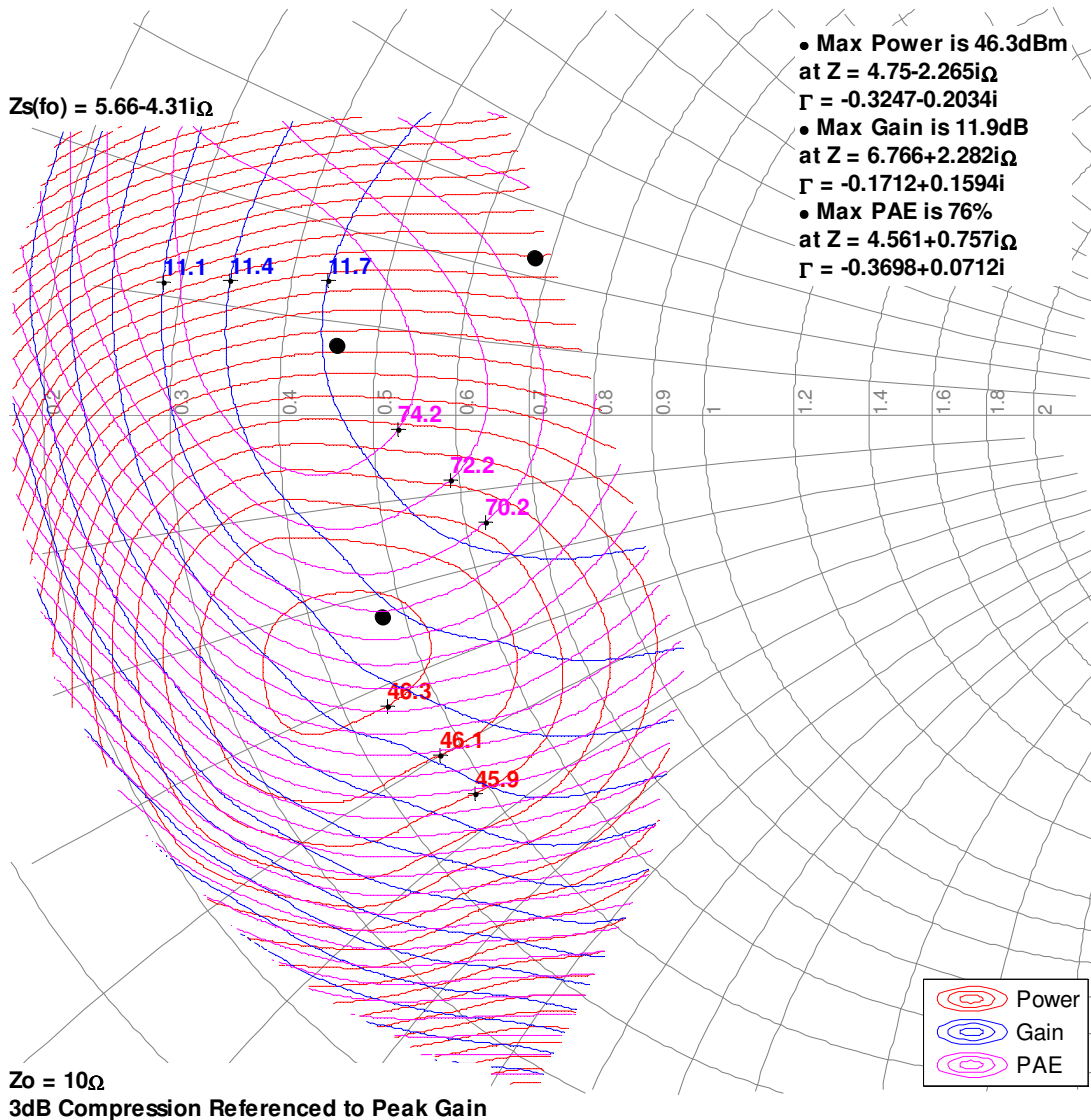


## Load Pull Smith Charts (1, 2, 3)

Notes:

1. Test Conditions:  $V_{DS} = 28\text{ V}$ ,  $I_{DQ} = 200\text{ mA}$
2. Test Signal: Pulse Width = 100  $\mu\text{sec}$ , Duty Cycle = 20%
3. See pg. 18 for load pull reference planes.

### 3GHz, Load-pull

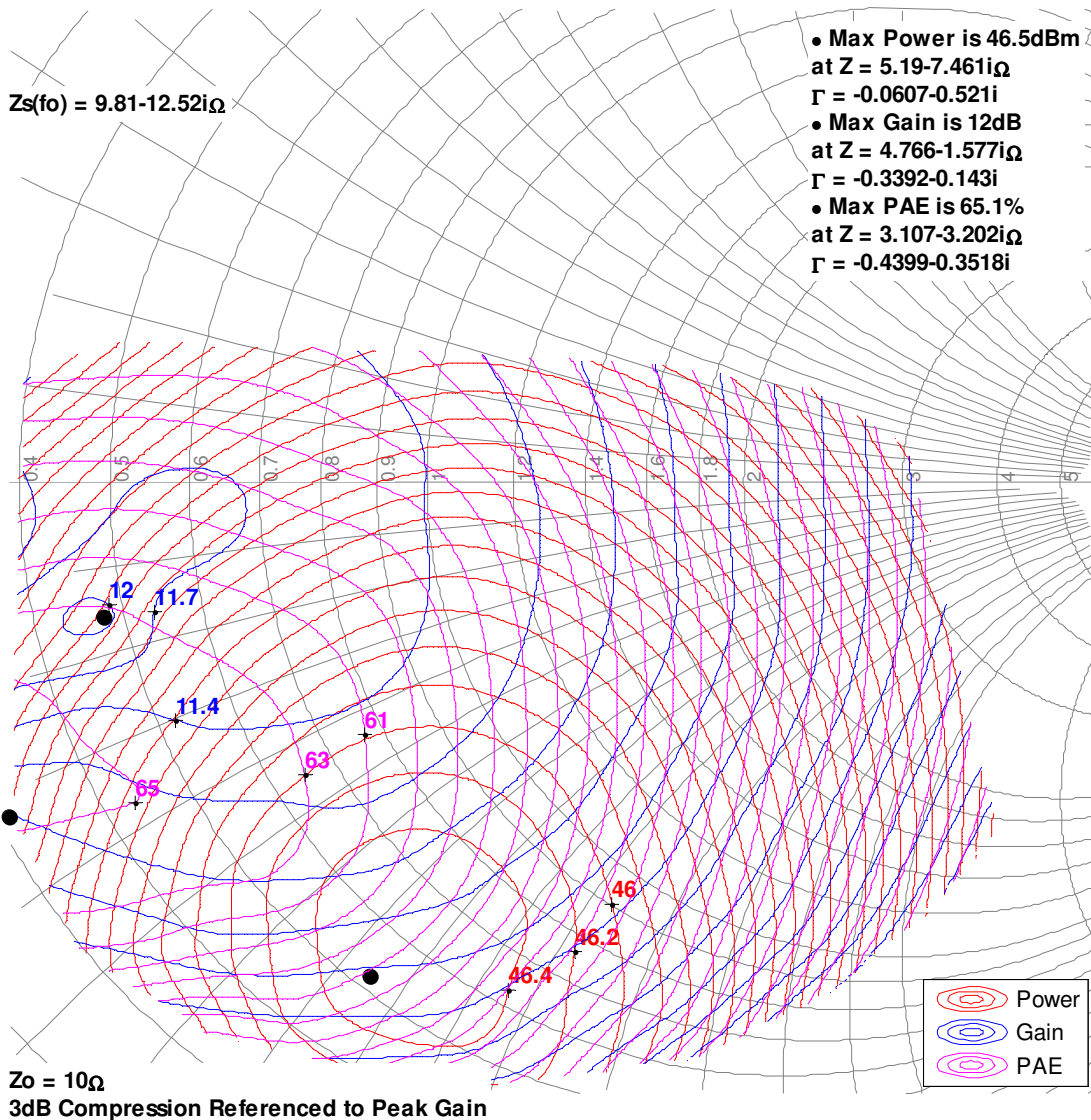


**Load Pull Smith Charts (1, 2, 3)**

Notes:

1. Test Conditions:  $V_{DS} = 28\text{ V}$ ,  $I_{DQ} = 200\text{ mA}$
2. Test Signal: Pulse Width = 100  $\mu\text{sec}$ , Duty Cycle = 20%
3. See pg. 18 for load pull reference planes.

**4GHz, Load-pull**

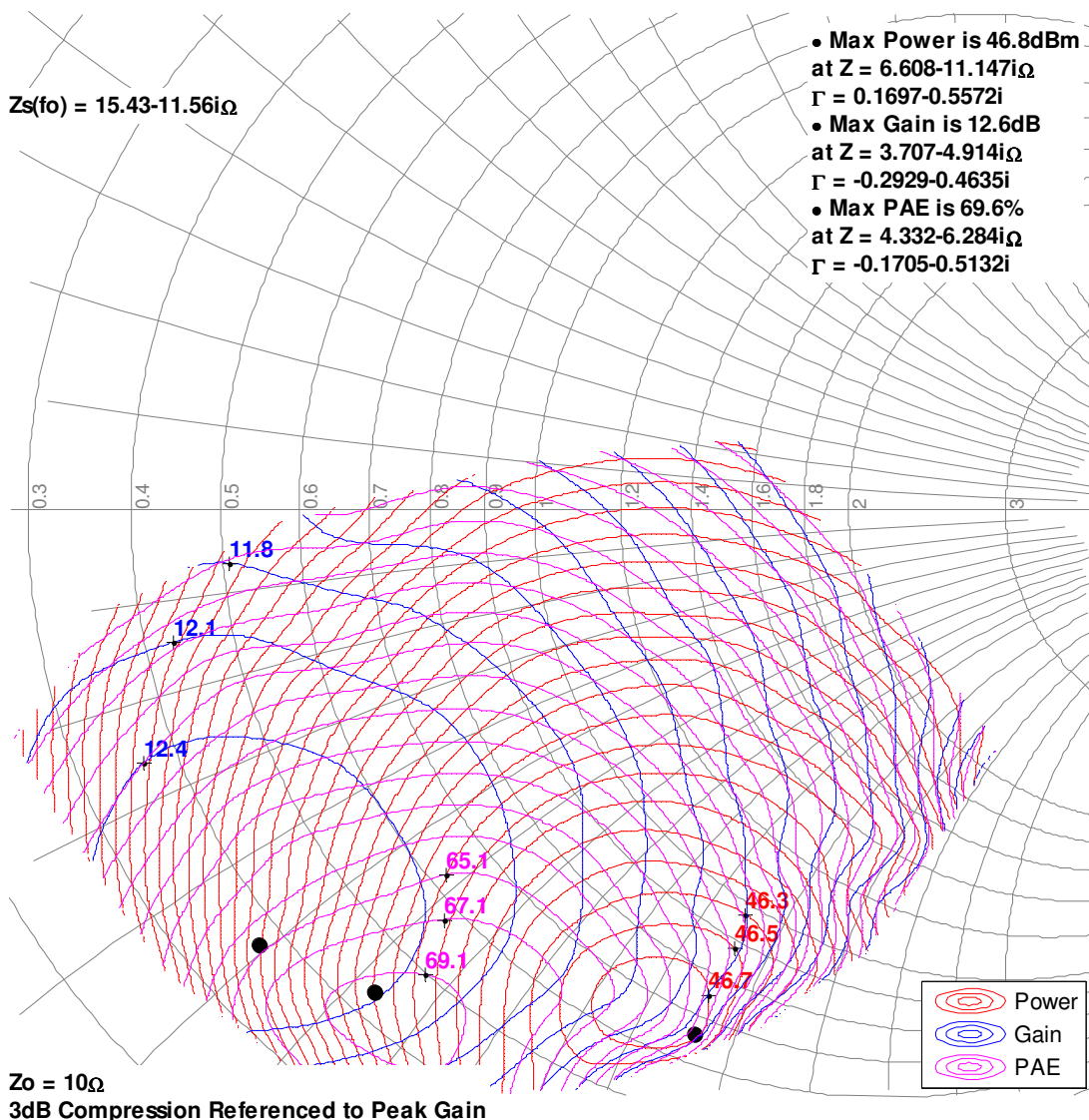


**Load Pull Smith Charts (1, 2, 3)**

Notes:

1. Test Conditions:  $V_{DS} = 28\text{ V}$ ,  $I_{DQ} = 200\text{ mA}$
2. Test Signal: Pulse Width = 100  $\mu\text{sec}$ , Duty Cycle = 20%
3. See pg. 18 for load pull reference planes.

**5GHz, Load-pull**

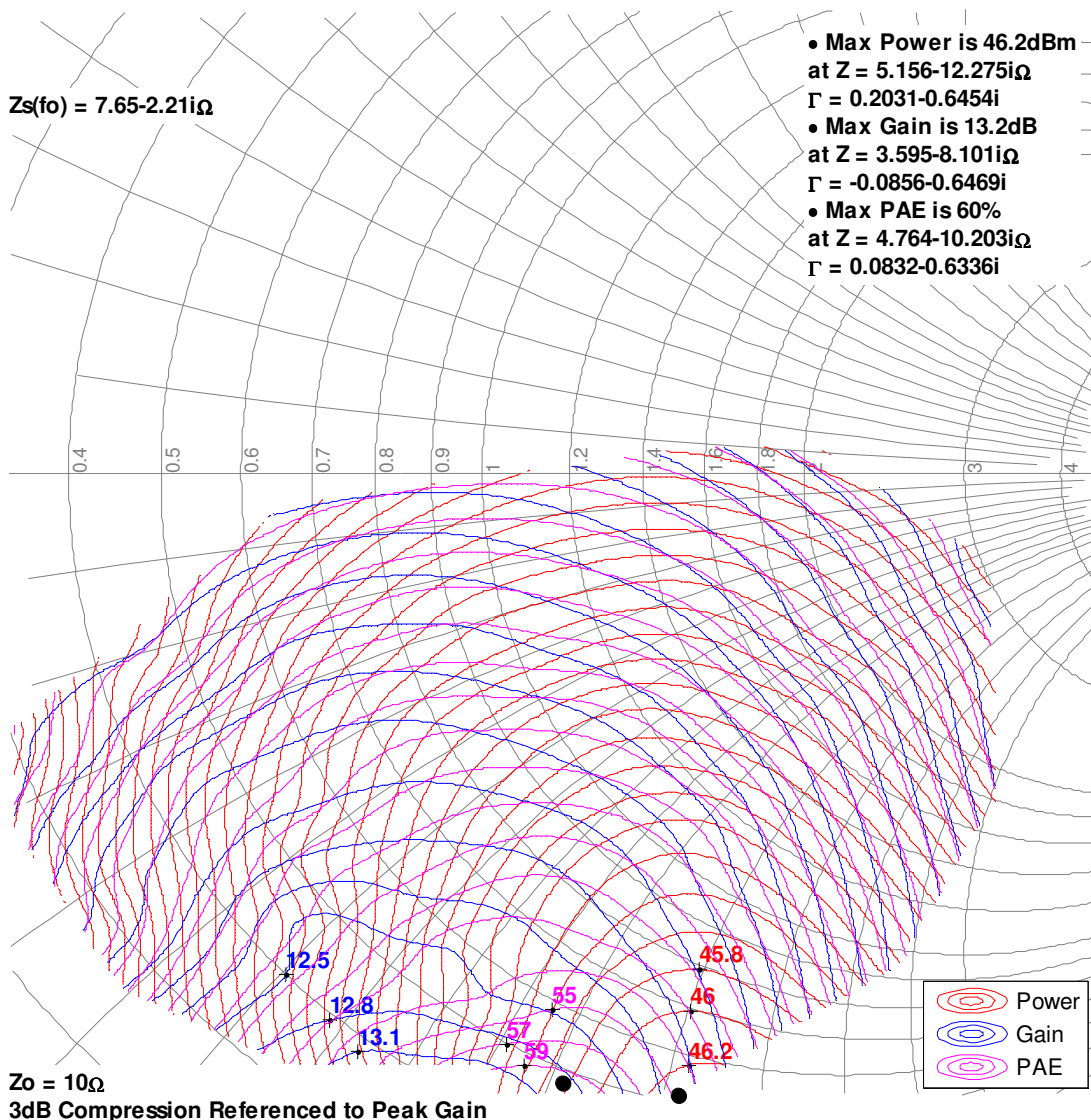


**Load Pull Smith Charts (1, 2, 3)**

Notes:

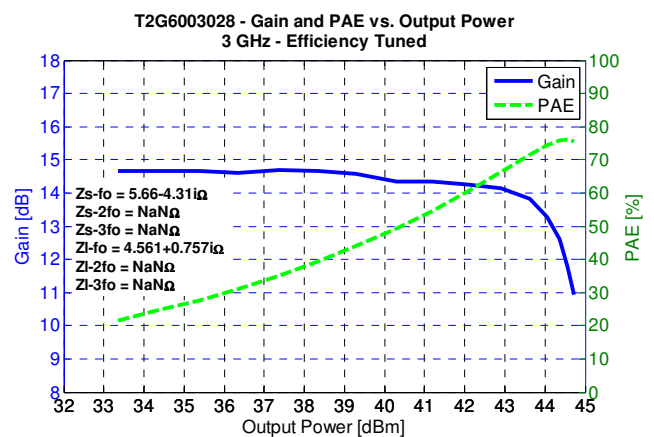
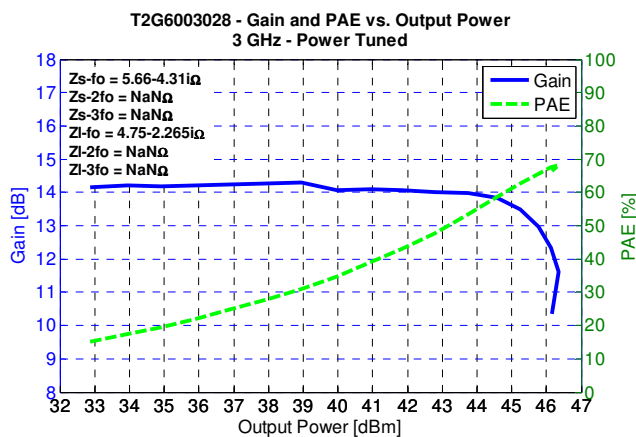
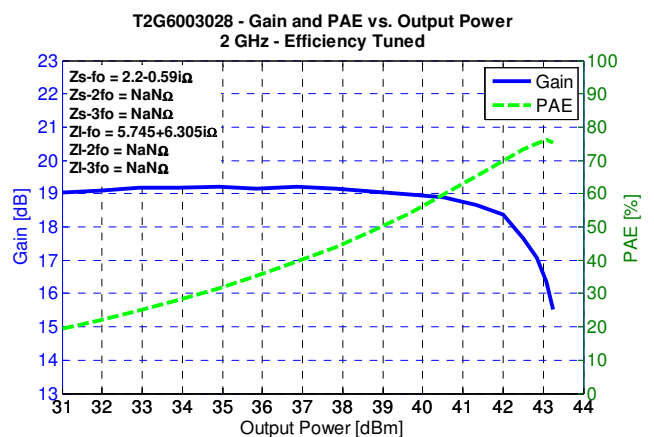
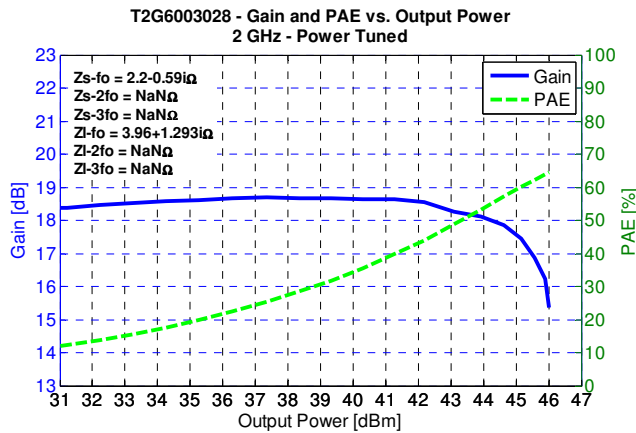
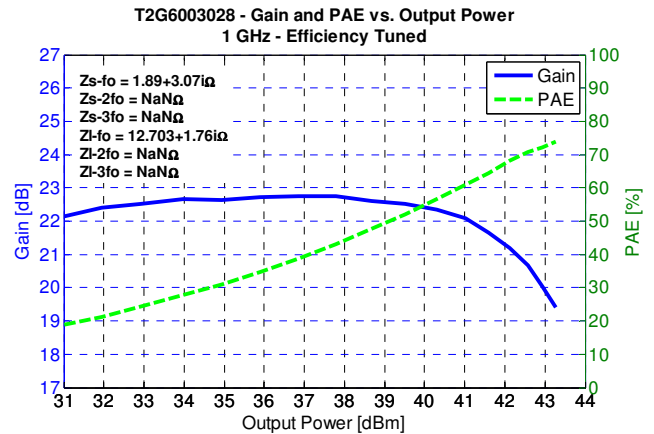
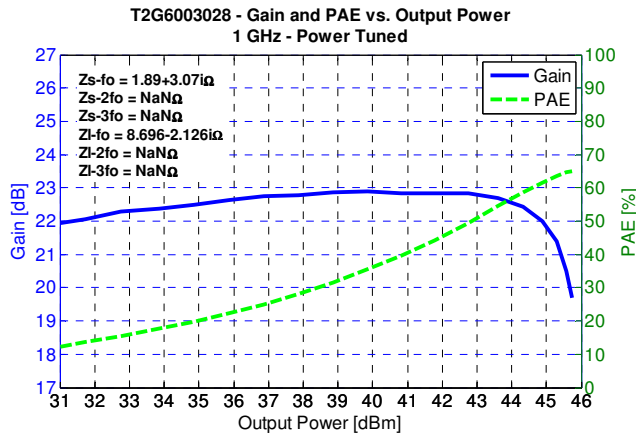
1. Test Conditions:  $V_{DS} = 28\text{ V}$ ,  $I_{DQ} = 200\text{ mA}$
2. Test Signal: Pulse Width =  $100\ \mu\text{sec}$ , Duty Cycle = 20%
3. See pg. 18 for load pull reference planes.

**6GHz, Load-pull**



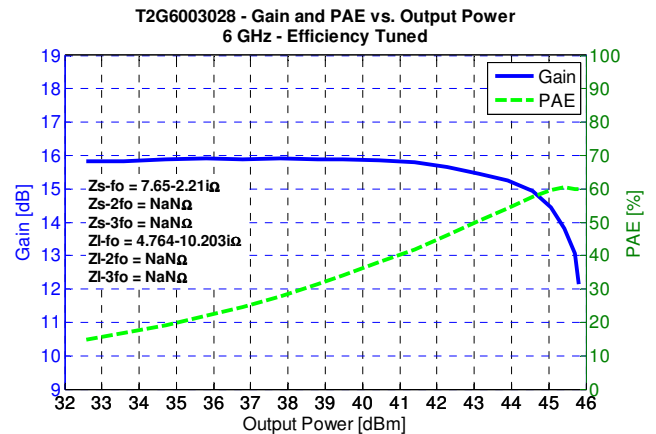
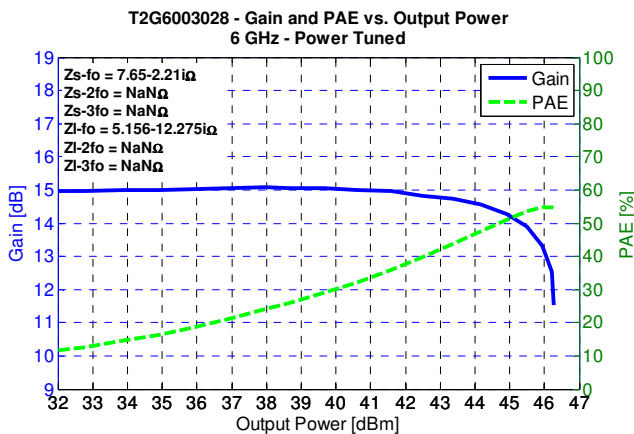
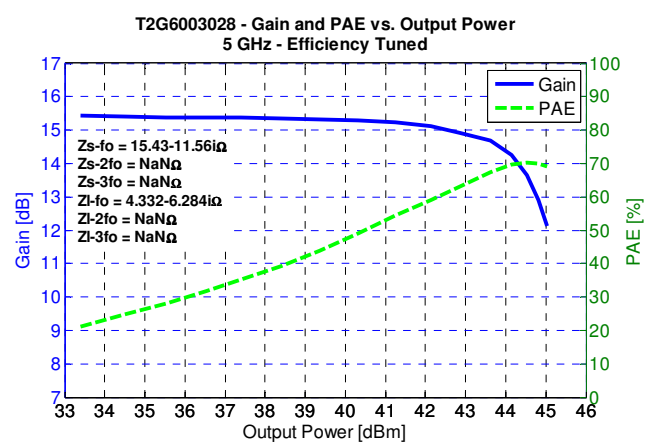
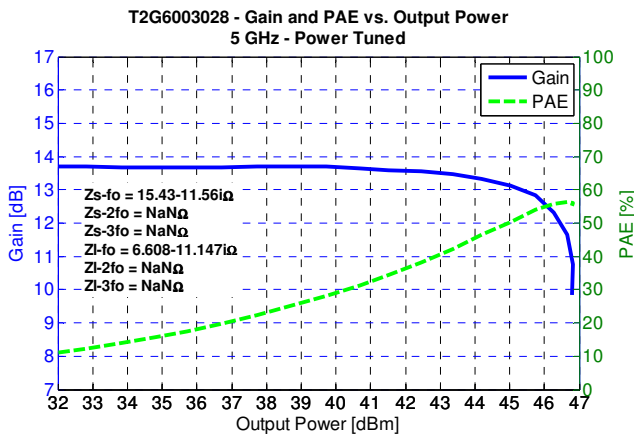
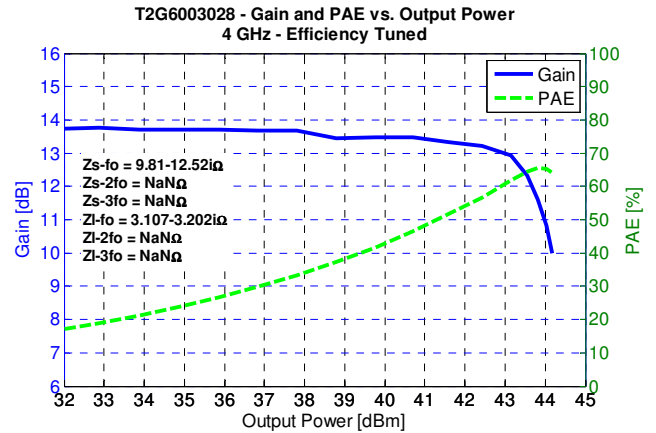
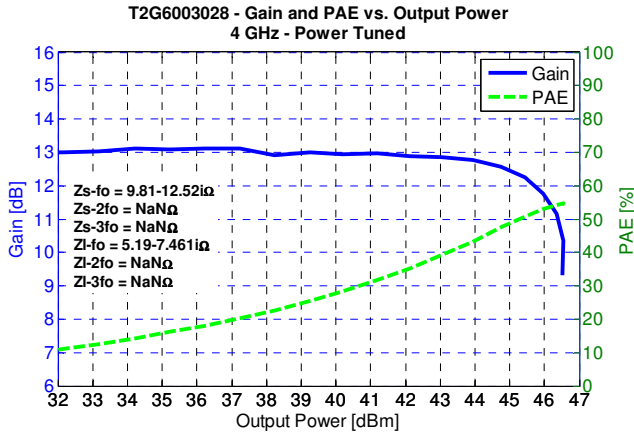
## Characterization Drive-up <sup>(1, 2)</sup>

- V<sub>d</sub> = 28 V, I<sub>dq</sub> = 200 mA, Pulse Width = 100 uS, Duty Cycle = 20%
- NaN means the parameter is either unavailable or undefined.



## Characterization Drive-up <sup>(1, 2)</sup>

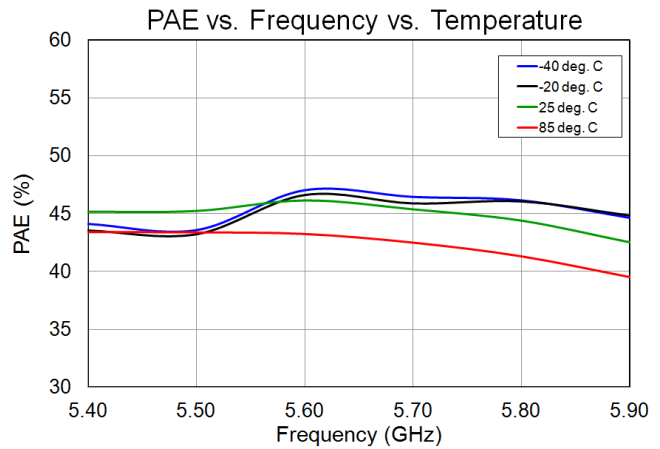
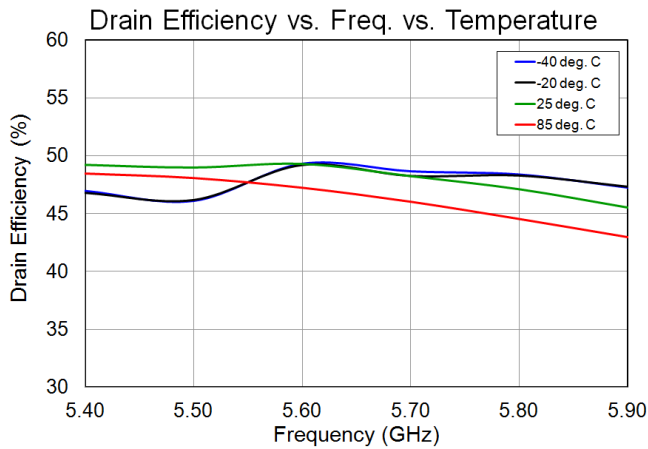
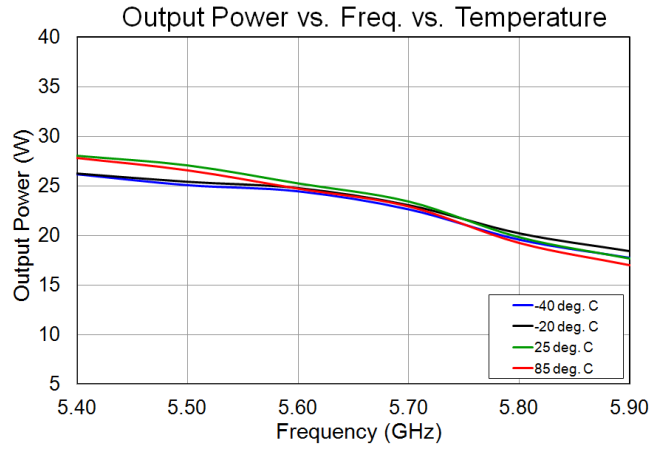
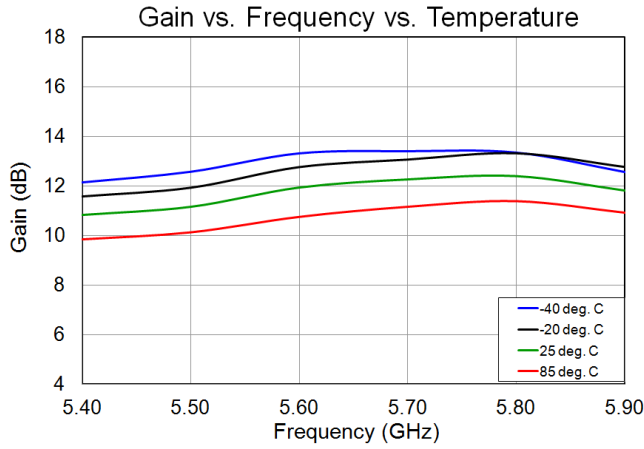
- V<sub>d</sub> = 28 V, I<sub>dq</sub> = 200 mA, Pulse Width = 100 uS, Duty Cycle = 20%
- NaN means the parameter is either unavailable or undefined.





## Performance Over Temperature (1, 2)

Performance measured in Qorvo's 5.4 GHz to 5.9 GHz Evaluation Board at 3 dB compression.



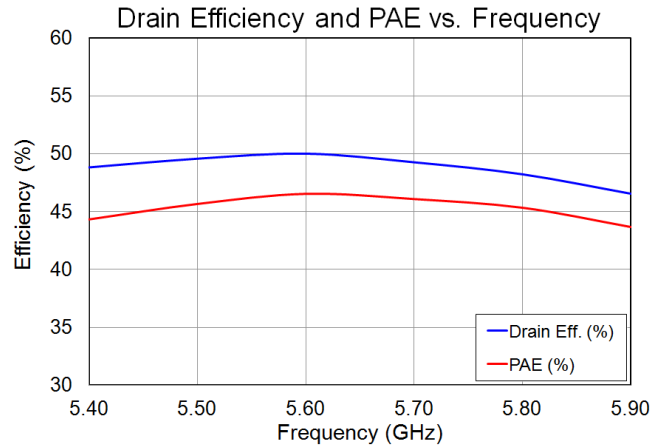
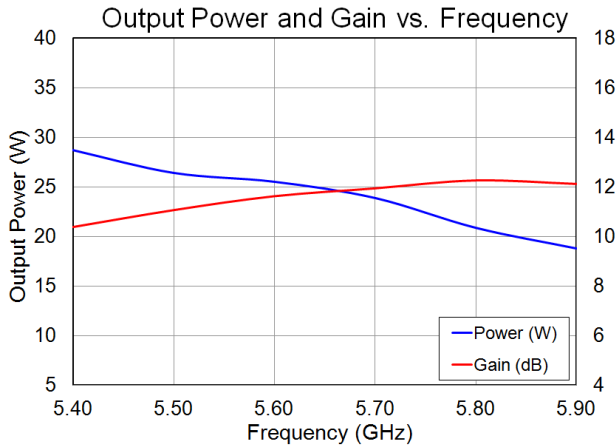
**Notes:**

1. Test Conditions:  $V_{DS} = 28\text{ V}$ ,  $I_{DQ} = 200\text{ mA}$
2. Test Signal: Pulse Width = 100  $\mu\text{s}$ , Duty Cycle = 20%



## Evaluation Board Performance (1, 2)

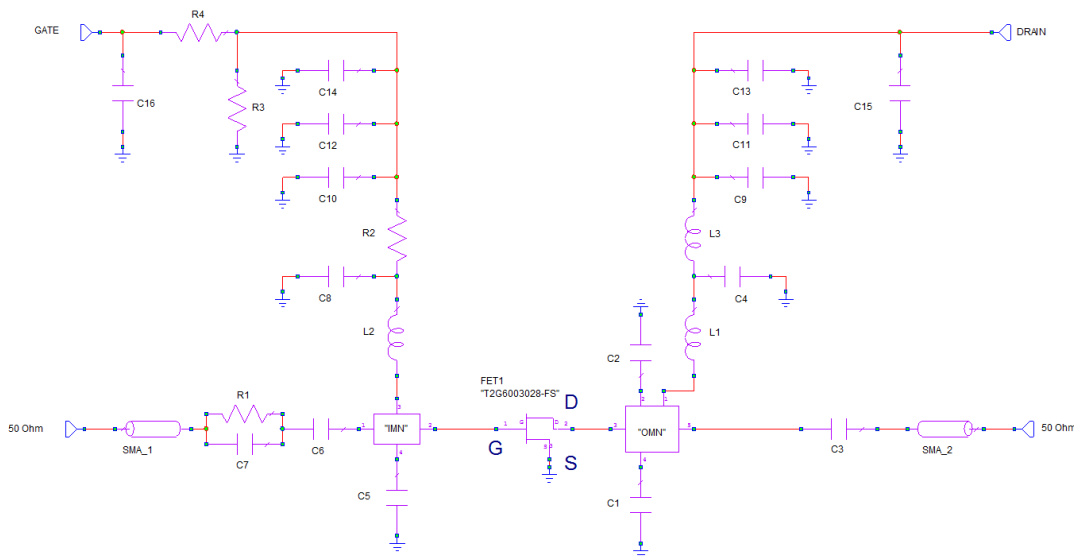
Performance at 3 dB Compression



Notes:

1. Test Conditions:  $V_{DS} = 28\text{ V}$ ,  $I_{DQ} = 200\text{ mA}$
2. Test Signal: Pulse Width =  $100\text{ }\mu\text{s}$ , Duty Cycle = 20 %

## Application Circuit



### Bias-up Procedure

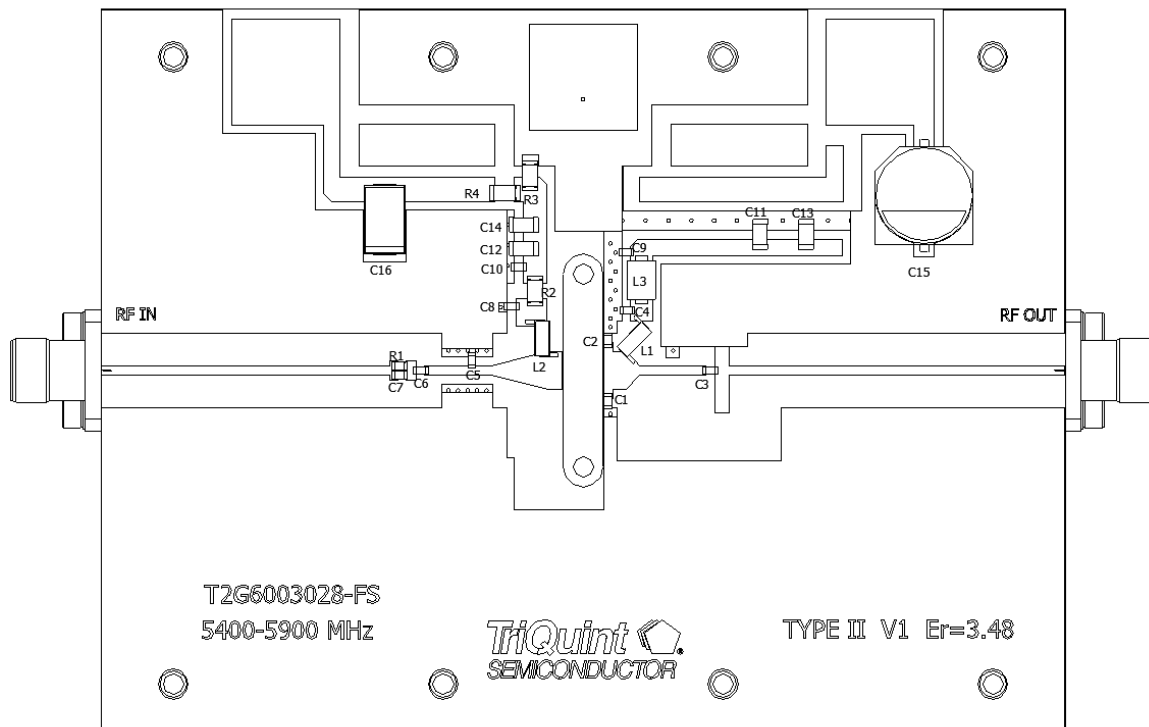
1. Set gate voltage ( $V_G$ ) to  $-5.0\text{ V}$ .
2. Set drain current ( $I_D$ ) limit to  $220\text{ mA}$ .
3. Set drain voltage ( $V_D$ ) to  $28\text{ V}$ .
4. Slowly increase  $V_G$  until quiescent  $I_D$  is  $200\text{ mA}$ .
5. Set drain current ( $I_D$ ) to  $2.8\text{ A}$ .
6. Apply RF signal.

### Bias-down Procedure

1. Turn off RF signal.
2. Turn off  $V_D$  and wait 1 second to allow drain capacitor discharge.
3. Turn off  $V_G$ .

## Evaluation Board Layout

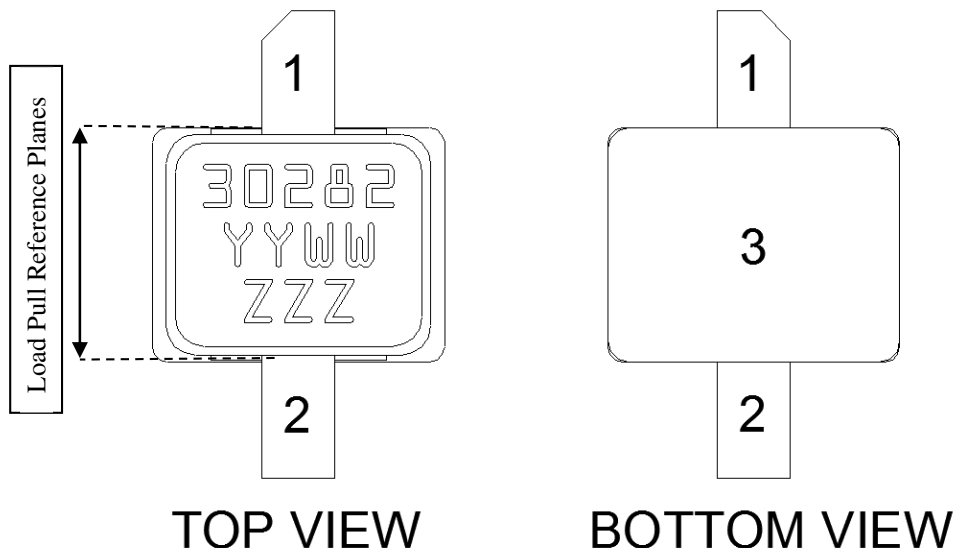
Top RF layer is 0.020" thick Rogers RO4350B,  $\epsilon_r = 3.48$ . The pad pattern shown has been developed and tested for optimized assembly at Qorvo Semiconductor. The PCB land pattern has been developed to accommodate lead and package tolerances.



## Bill of Materials

Reference Design	Value	Qty	Manufacturer	Part Number
C1	0.3 pF	1	ATC	ATC600S0R3
C2	0.2 pF	1	ATC	ATC600S0R2
L1, L2	8.8 NH	2	COILCRAFT	1606-8
C3, C4, C6, C7, C8	3 pF	5	ATC	ATC600S3R0
C5	0.4 pF	1	ATC	ATC600S0R5
R1	97.6 Ohms	1	Venkel	CR0604-16w-97R6FT
R2	4.7 Ohms	1	Newark	37C0064
R3	330 Ohms	1	Newark	TNPW1206330RBT9ET1-E3
R4	50 Ohms	1	ATC	CRCW120651R0FKEA
C9, C10	220 pF	2	AVX	AVX06035C22KAT2A
C11, C12	2200 pF	2	Vitramon	VJ1206Y222KXA
C13, C14	22000 pF	2	Vitramon	VJ1206Y223KXA
C15	220 uF	1	United Chemi-Con	EMVY500ADA221MJA0G
C16	1.0 uF	1	Allied	541-1231
L3	48 Ohm	1	Ferrite, Laird Tech.	28F0121-0SR-10

## Pin Layout



**Note:**

The T2G6003028-FS will be marked with the “30282” designator and a lot code marked below the part designator. The “YY” represents the last two digits of the calendar year the part was manufactured, the “WW” is the work week of the assembly lot start, and the “ZZZ” is an auto-generated number.

## Pin Description

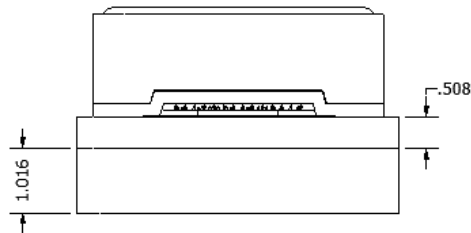
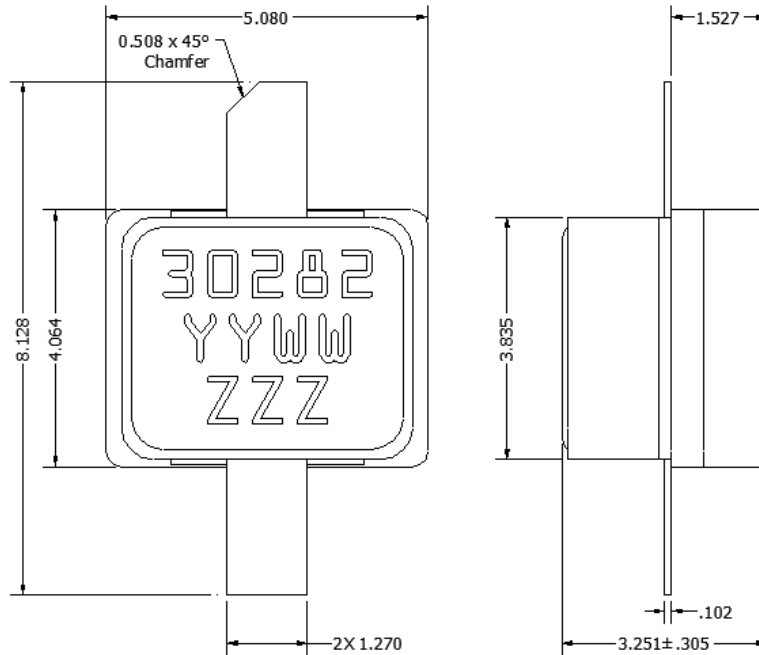
Pin	Symbol	Description
1	$V_D$ / RF OUT	Drain voltage / RF Output matched to 50 ohms; see EVB Layout on page 17 as an example.
2	$V_G$ / RF IN	Gate voltage / RF Input matched to 50 ohms; see EVB Layout on page 17 as an example.
3	Flange	Source connected to ground; see EVB Layout on page 17 as an example.

**Notes:**

Thermal resistance measured to bottom of package

## Mechanical Information

All dimensions are in millimeters.



TOLERANCES  
 X.XX = ± .25  
 X.XXX = ± .127  
 X.XXXX = ± .0254  
 ANGLES = 0.5°

**Note:**

This package is lead-free/RoHS-compliant. The plating material on the leads is NiAu. It is compatible with both lead-free (maximum 260 °C reflow temperature) and tin-lead (maximum 245°C reflow temperature) soldering processes.

## Product Compliance Information

### ESD Sensitivity Ratings



Caution! ESD-Sensitive Device

ESD Rating: Class 1A  
 Value: Passes  $\geq 250$  V to  $< 500$  V max.  
 Test: Human Body Model (HBM)  
 Standard: JEDEC Standard JESD22-A114

### MSL Rating

Level 3 at  $+260$  °C convection reflow  
 The part is rated Moisture Sensitivity Level 3 at  $260$  °C per JEDEC standard IPC/JEDEC J-STD-020.

### ECCN

US Department of Commerce EAR99

### Solderability

Compatible with the latest version of J-STD-020, Lead free solder,  $260$  °C

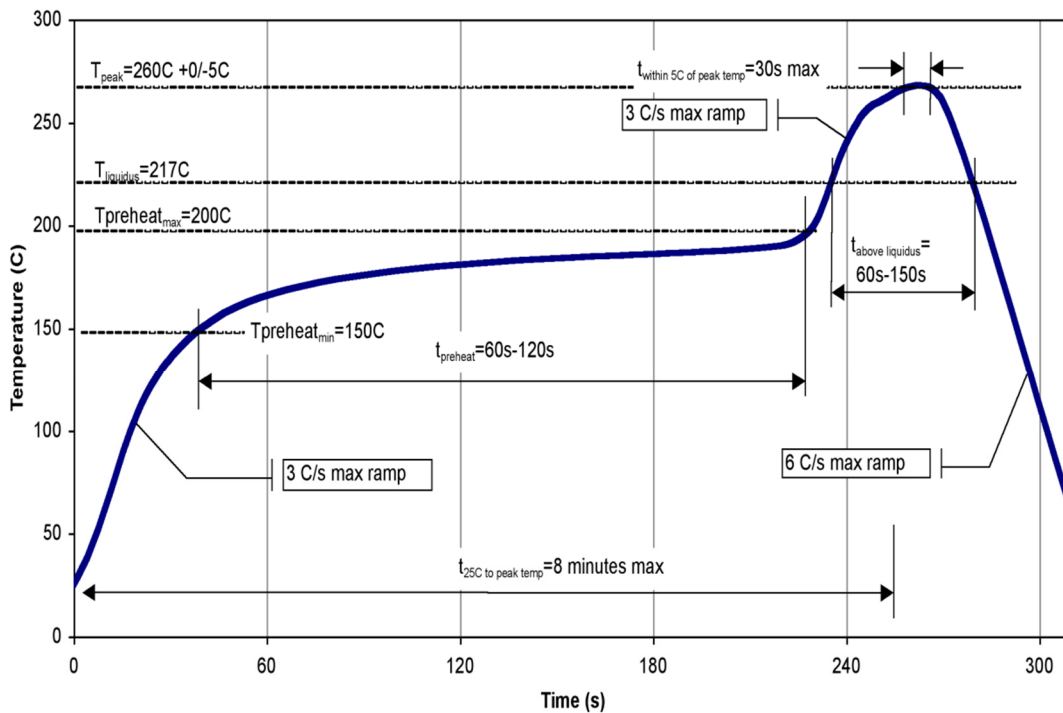
### RoHS Compliance

This part is compliant with EU 2002/95/EC RoHS directive (Restrictions on the Use of Certain Hazardous Substances in Electrical and Electronic Equipment).

This product also has the following attributes:

- Lead Free
- Halogen Free (Chlorine, Bromine)
- Antimony Free
- TBBP-A ( $C_{15}H_{12}Br_4O_2$ ) Free
- PFOS Free
- SVHC Free

## Recommended Soldering Temperature Profile





# T2G6003028-FS

30W, 28V DC – 6 GHz, GaN RF Power Transistor

## Contact Information

For the latest specifications, additional product information, worldwide sales and distribution locations, and information about Qorvo:

Web: [www.qorvo.com](http://www.qorvo.com) Tel: +1.972.994.8465  
Email: [info-sales@qorvo.com](mailto:info-sales@qorvo.com) Fax: +1.972.994.8504

For technical questions and application information: Email: [info-products@qorvo.com](mailto:info-products@qorvo.com)

## Important Notice

The information contained herein is believed to be reliable. Qorvo makes no warranties regarding the information contained herein. Qorvo assumes no responsibility or liability whatsoever for any of the information contained herein. Qorvo assumes no responsibility or liability whatsoever for the use of the information contained herein. The information contained herein is provided "AS IS, WHERE IS" and with all faults, and the entire risk associated with such information is entirely with the user. All information contained herein is subject to change without notice. Customers should obtain and verify the latest relevant information before placing orders for Qorvo products. The information contained herein or any use of such information does not grant, explicitly or implicitly, to any party any patent rights, licenses, or any other intellectual property rights, whether with regard to such information itself or anything described by such information.

Qorvo products are not warranted or authorized for use as critical components in medical, life-saving, or life-sustaining applications, or other applications where a failure would reasonably be expected to cause severe personal injury or death.

Компания «Life Electronics» занимается поставками электронных компонентов импортного и отечественного производства от производителей и со складов крупных дистрибьюторов Европы, Америки и Азии.

С конца 2013 года компания активно расширяет линейку поставок компонентов по направлению коаксиальный кабель, кварцевые генераторы и конденсаторы (керамические, пленочные, электролитические), за счёт заключения дистрибьюторских договоров

Мы предлагаем:

- Конкуренспособные цены и скидки постоянным клиентам.
- Специальные условия для постоянных клиентов.
- Подбор аналогов.
- Поставку компонентов в любых объемах, удовлетворяющих вашим потребностям.
- Приемлемые сроки поставки, возможна ускоренная поставка.
- Доставку товара в любую точку России и стран СНГ.
- Комплексную поставку.
- Работу по проектам и поставку образцов.
- Формирование склада под заказчика.
- Сертификаты соответствия на поставляемую продукцию (по желанию клиента).
- Тестирование поставляемой продукции.
- Поставку компонентов, требующих военную и космическую приемку.
- Входной контроль качества.
- Наличие сертификата ISO.

В составе нашей компании организован Конструкторский отдел, призванный помогать разработчикам, и инженерам.

Конструкторский отдел помогает осуществить:

- Регистрацию проекта у производителя компонентов.
- Техническую поддержку проекта.
- Защиту от снятия компонента с производства.
- Оценку стоимости проекта по компонентам.
- Изготовление тестовой платы монтаж и пусконаладочные работы.



Тел: +7 (812) 336 43 04 (многоканальный)

Email: [org@lifeelectronics.ru](mailto:org@lifeelectronics.ru)